

RAL CSDG Future Interests

Technologies

- 3D Integration (MPW now available)
- 65nm
- SPADs
- Coatings for conversion (scintillators, IR etc.)
- Depleted substrates

IP Development

- 10MSPS ADC
- High Speed Serialisers
- Greater system integration
- Greater re-use of IP
- Low power front end
- Serial Powering
- On-chip data compression